3. (amended) The small memory card according to claim 1, wherein 〔 the revealed glue layer encapsulated the lower surface of a plurality of the memory chips. 〕 the lower surface of memory chips are exposed from the glue layer.

ABSTRAT OF THE DISCLOSURE

A small memory card includes a substrate, a plurality of memory chips, a plurality of wires, and a glue layer, the substrate is formed with a plurality of through slots, then the plurality of memory chips 〔 be 〕 are mounted on the substrate, so that the plurality of bounding pads of the memory chip are exposed from through slot of the substrate, 〔 from through slot may be revealed 〕 〔 and use a 〕 the plurality of wires are electrically connected to the substrate, 〔 finally use 〕 the glue layer 〔 encapsulating a 〕 is encapsulated the plurality of memory chips at the same time. Thus, the small memory card of present invention has small packed volume, and the manufacturing processes may be convenient.

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